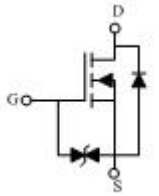
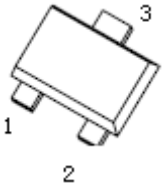
Feature

- 60V,0.3A
  $R_{DS(ON)}$ <2.2Ω @V_{GS}=10V TYP:1.8Ω
  $R_{DS(ON)}$ <2.6Ω @V_{GS}=4.5V TYP:2.2Ω
- Advanced TrenchTechnology
- Lead free product is acquired
- ESD Protected Up to 2.0KV(HBM)



Schematic diagram



1. GATE
2. SOURCE
3. DRAIN

SOT-323

Application

- Networking
- Load Switching
- Logic Level shift

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
2K260N3	AP2K260N3	SOT-323	7 inch	-	3000

ABSOLUTE MAXIMUM RATINGS (T_J=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current (T_a =25℃)	I_D	0.3	A
Continuous Drain Current (T_a =100℃)	I_D	0.2	A
Pulsed Drain Current	I_{DM}	1.2	A
Power Dissipation	P_D	0.2	W
Thermal Resistance from Junction to Ambient(4)	$R_{\theta JA}$	625	℃/W
Junction Temperature	T_J	150	℃
Storage Temperature	T_{STG}	-55~ +150	℃

MOSFET ELECTRICAL CHARACTERISTICS(T_J=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D =250μA	60	-	-	V
Zero gate voltage drain current	I_{DSS}	V_{DS} =60V, V_{GS} = 0V	-	-	1	μA
Gate-body leakage current	I_{GSS}	V_{GS} =±20V,V_{DS} = 0V	-	-	±10	μA
Gate threshold voltage(3)	$V_{GS(th)}$	V_{DS} =V_{GS}, I_D =250μA	1.0	1.6	2.5	V
Drain-source on-resistance(3)	$R_{DS(on)}$	V_{GS} =10V, I_D =0.1A	-	1.8	2.2	Ω
		V_{GS} =4.5V, I_D =0.1A	-	2.2	2.6	
Dynamic characteristics						
Input Capacitance	C_{iss}	V_{DS} =10V, V_{GS} =0V, f =1MHz	-	28	-	pF
Output Capacitance	C_{oss}		-	11	-	
Reverse Transfer Capacitance	C_{rss}		-	4	-	
Switching characteristics						
Turn-on delay time	$t_{d(on)}$	V_{DD}=10V, I_D=0.2A, V_{GS}=10V, R_G=3.3Ω	-	2	-	ns
Turn-on rise time	t_r		-	15	-	
Turn-off delay time	$t_{d(off)}$		-	7	-	
Turn-off fall time	t_f		-	20	-	
Total Gate Charge	Qg	VDS=30V, ID=0.3A, VGS=10V	-	1.7	-	nC
Gate-Source Charge	Qgs		-	0.3	-	
Gate-Drain Charge	Qgd		-	0.6	-	
Source-Drain Diode characteristics						
Diode Forward voltage(3)	V_{DS}	V_{GS} =0V, I_S=0.3A	-	-	1.2	V
Diode Forward current(4)	I_S		-	-	0.3	A

Notes:

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. Pulse Test: pulse width≤300μs, duty cycle≤2%
3. Surface Mounted on FR4 Board,t≤10 sec

Test Circuit

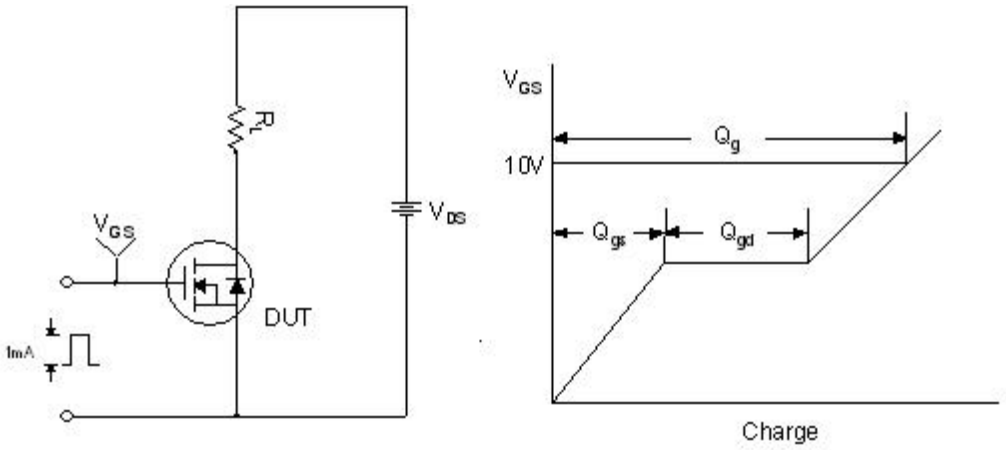


Figure 1. Gate Charge Test Circuit & Waveform

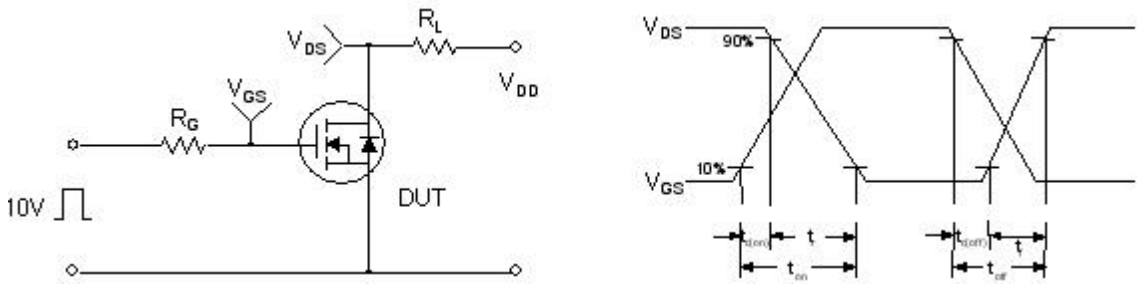


Figure 2. Resistive Switching Test Circuit & Waveforms

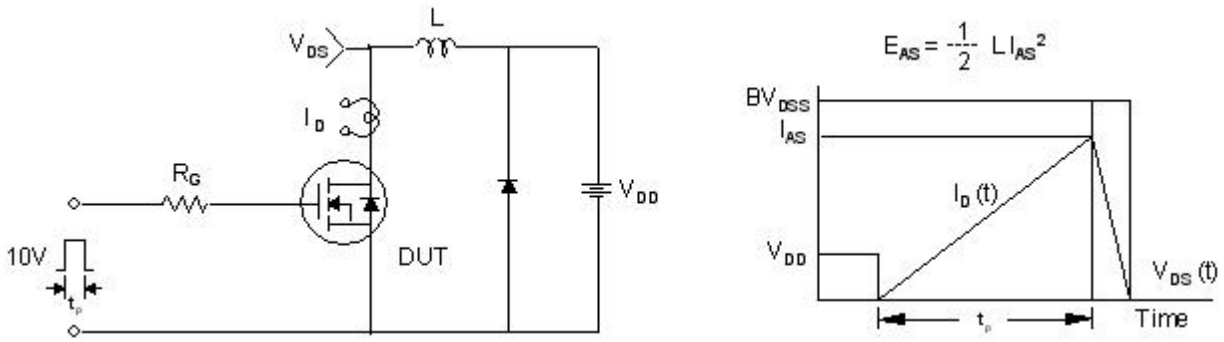


Figure 3. Unclamped Inductive Switching Test Circuit & Waveforms

Typical Performance Characteristics

Figure1: Output Characteristics

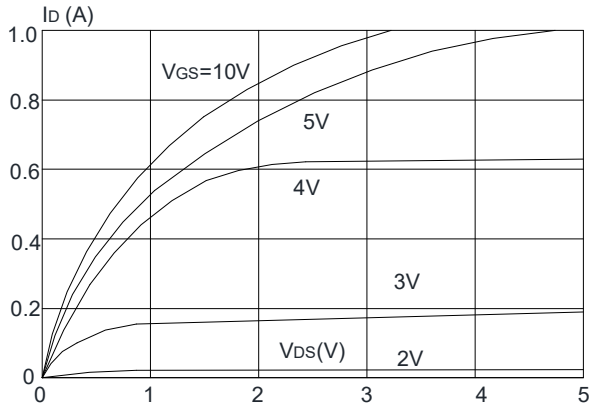


Figure 2: Typical Transfer Characteristics

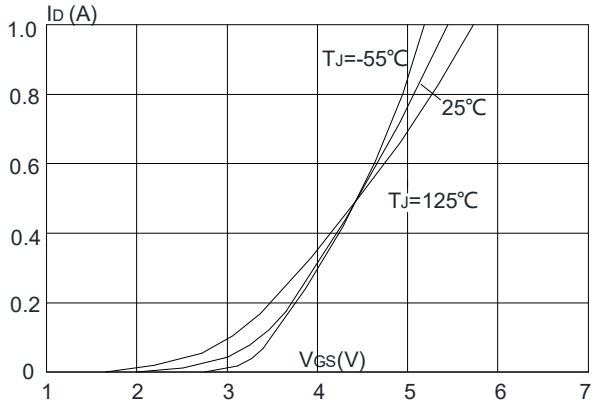


Figure 3: On-resistance vs. Drain Current

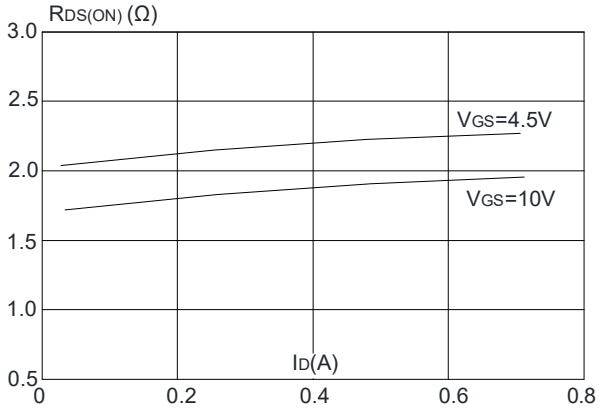


Figure 4: Body Diode Characteristics

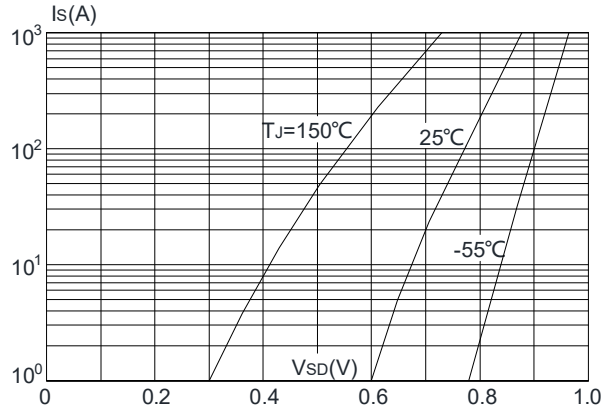


Figure 5: Gate Charge Characteristics

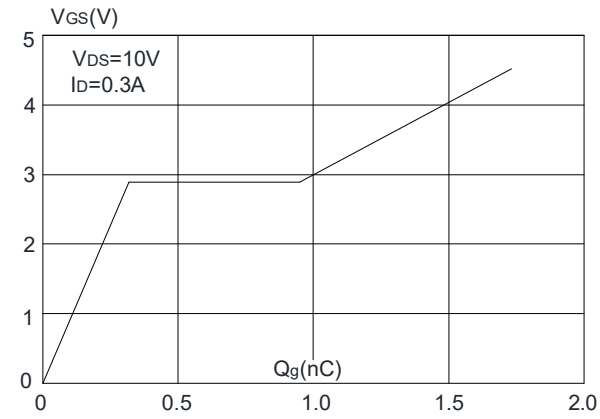


Figure 6: Capacitance Characteristics

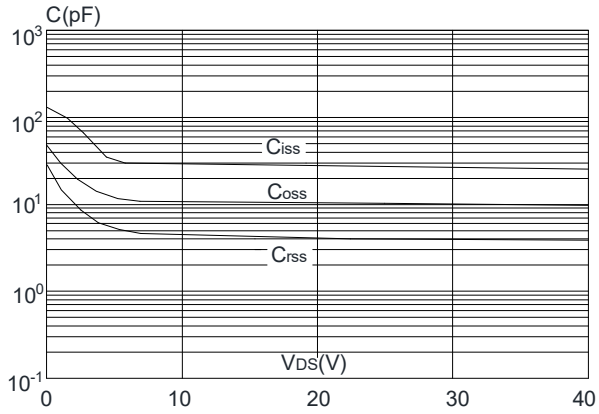


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

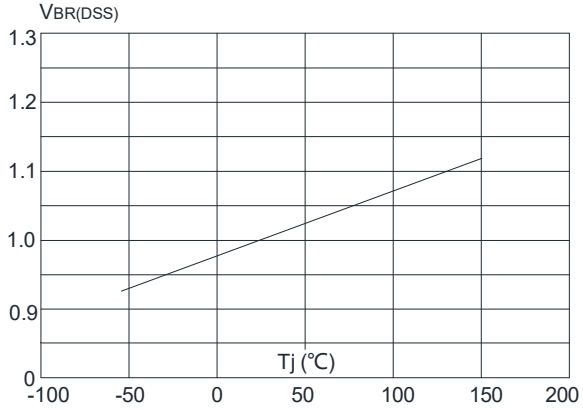


Figure 8: Normalized on Resistance vs. Junction Temperature

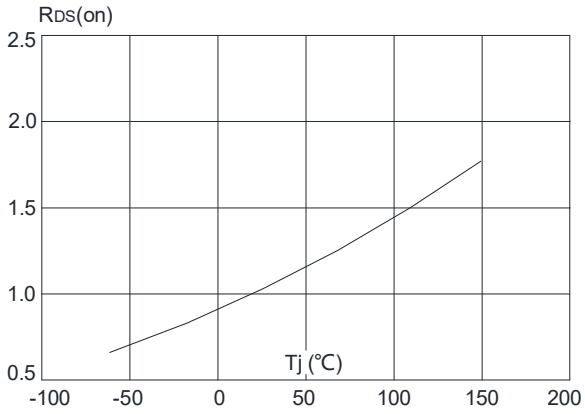


Figure 9: Maximum Safe Operating Area

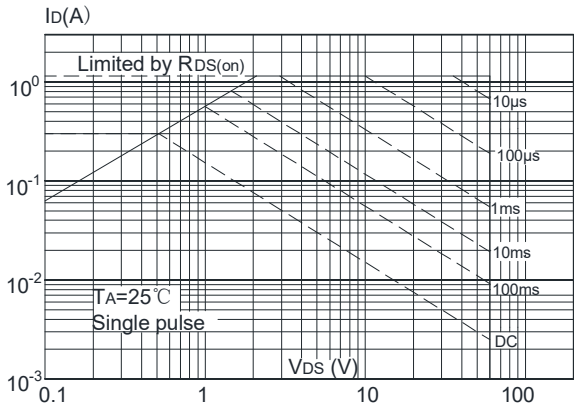


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

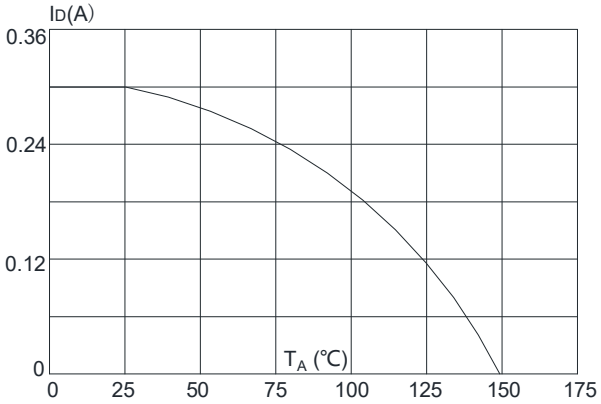
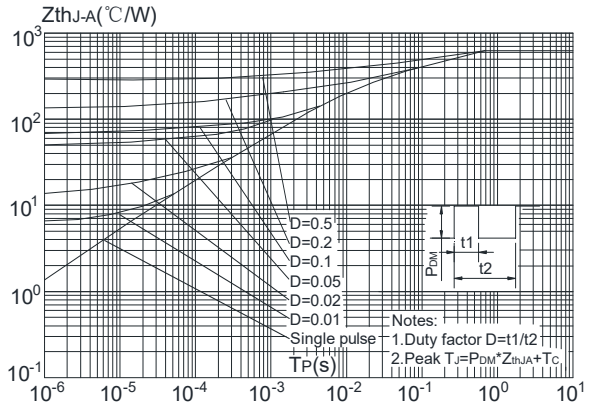
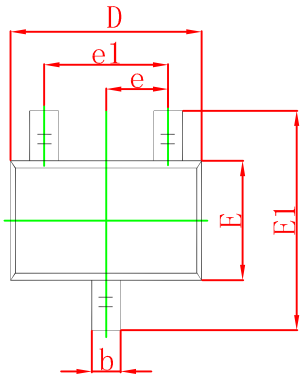
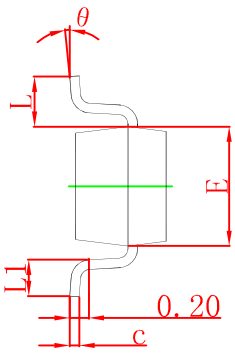


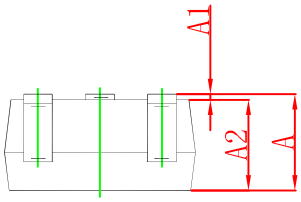
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



SOT-323 Package Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.200	0.400	0.008	0.016
c	0.080	0.150	0.003	0.006
D	2.000	2.200	0.079	0.087
E	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650 TYP		0.026 TYP	
e1	1.200	1.400	0.047	0.055
L	0.525 REF		0.021 REF	
L1	0.260	0.460	0.010	0.018
θ	0°	8°	0°	8°

Revision History

Revision	Release	Remark
V1.0	2023/06/01	Initial Release

Disclaimer

The information given in this document describes the independent performance of the product,but similar performance is not guaranteed under other working conditions,and cannot be guaranteed when installed with other products or equipment.To achieve the required performance of the product in actual scenarios,the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings,operating conditions,or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability.Customers using or selling these products for use in medical,life-saving,or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements,the information described or contained herein may be changed without prior notice.